

JFP Scriber S100

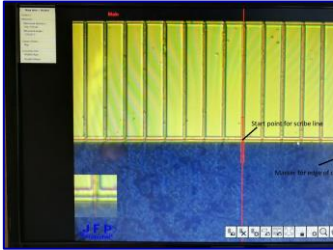


The machines which require minimal training to operate



Wafer Scriber/Breaker

MADE IN FRANCE



Video



Camera Process



Click the following link to view the video
<https://www.youtube.com/watch?v=LIFvZv267tA>

The Scribe 100 is an unique machine designed for scribing & breaking of delicate die, such GaAs & silicon chip. Very flexible and uses the scribe and break sequence that keeps the finished die clean and free from damage.

During the breaking mode, the scribe 100 uses the rubber to hold the die as the linear knife is raised to break along the core line. The film prevents contamination or stress to the die.

All parameters are set from the control key boards, the machine is robust, vibration free and requires minimal training to operate.

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SCRIBING HEAD

- Z motion with adjustable angle
- Adjustable scribing force from 3gr up to 100gr; constant weight
- Diamond Tool: Adjustable for angle & rotation
- Tool Offset with cross-hair

WAFER TABLE

- Wafer chuck till 4",
- Die Size: Minimum 100µm square up to 10mmx10mm
- Wafer thickness: 50µm and up
- Manual rotation 90 degrees
- Rotation alignment by micrometric screw
- X Y Table / resolution 0,23µm
- Motion control with progressive joystick weight

VISION SYSTEM

- Optics & magnification compatible with application
- Alignment: Programmable area / Manual
- TFT monitors 17" and 21" and Color camera Ultra High definition
- Electronic Zoom X10
- LED lighting

BREAKER

- Break mode: operator control or automatic
- Breaking mode: Using top Rubber and bottom cutter

PARAMETERS

- Step Index and vertical interval
- Y scribe speed from 0.1 to 20 mm/sec
- Scribing length programmable
- Repeat scribe
- Number of scribe
- Component number
- Touchdown speed
- Cutter speed
- Cut counter

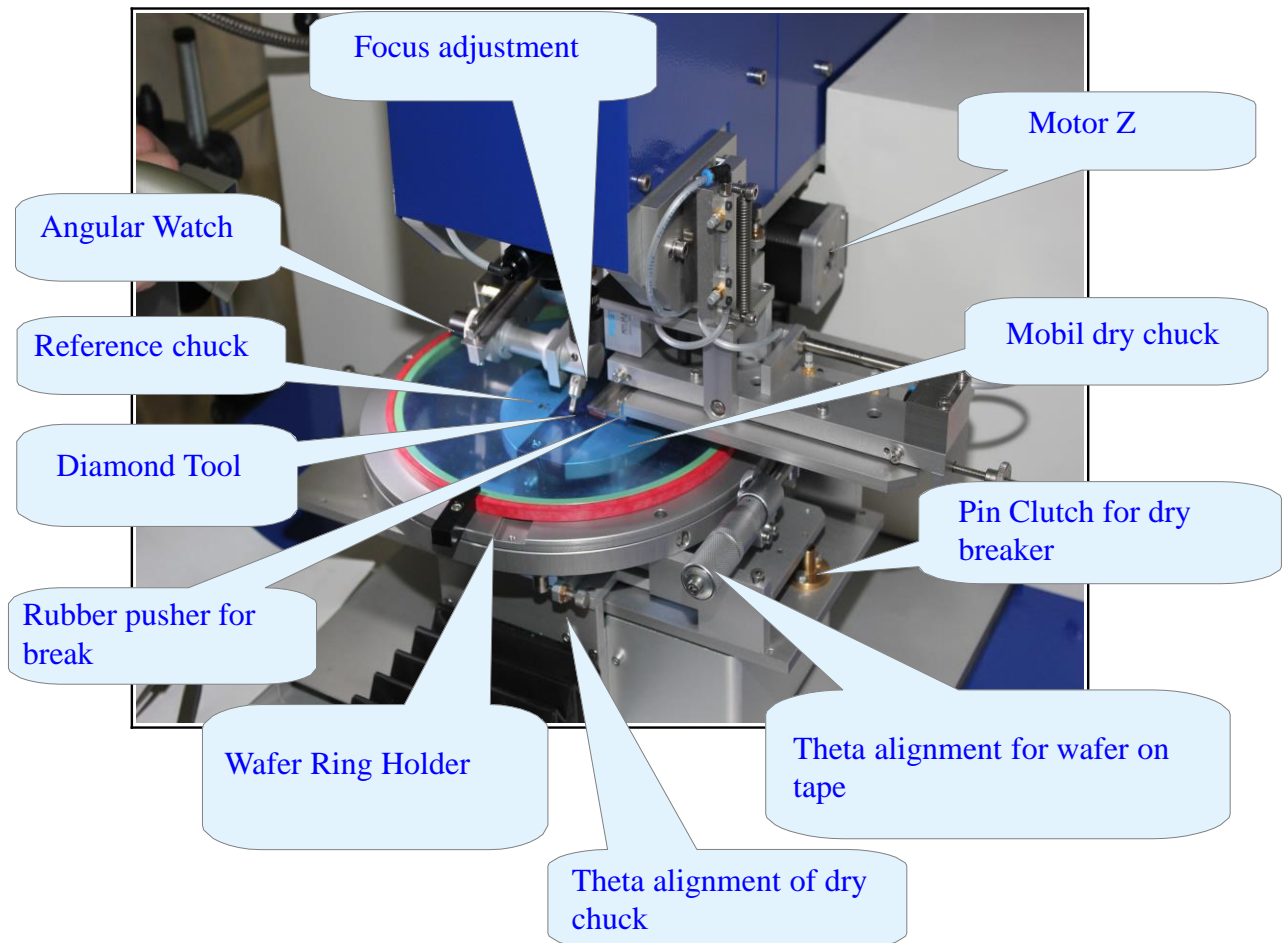
TECHNICAL SPECIFICATION

Power: 100 / 230VAC 0,5 kWatt
Air: 70psi
Vacuum: 60%
Dimensions: 650x820x130mm (25"x32"x5")
Weight: 70kg

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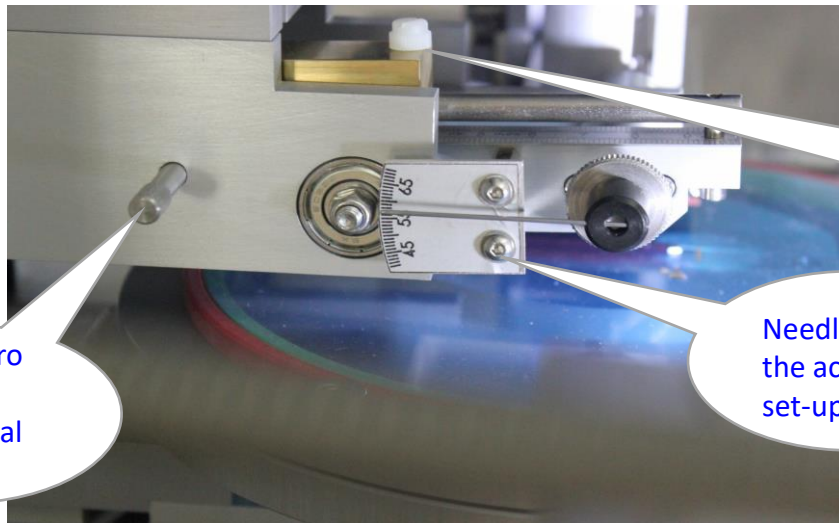


- Easy focus adjustment, done with thumbscrew.
- Regular scribe capability on tape (+ rings), programmed Z Motor.
- Standard Diamond Tool, angular adjustment and spin rotation correction. This is to achieve scribe and break of small parts, as laser bars, or laser diodes, Wafer Rotation alignment done with a micrometer, "Theta alignment for wafer on tape"
- Reference chuck : Parts to be scribed are located on this reference chuck (dry mode and tape mode as well).
- Mobil dry chuck : "no tape application"
 - used to move large parts, as a wafer, to make quarters, or large strips
 - this chuck is linked to motorized X using a special Pin clutch...
 - this chuck can do local theta alignment of part to be processed, using the "Theta alignment of dry chuck.

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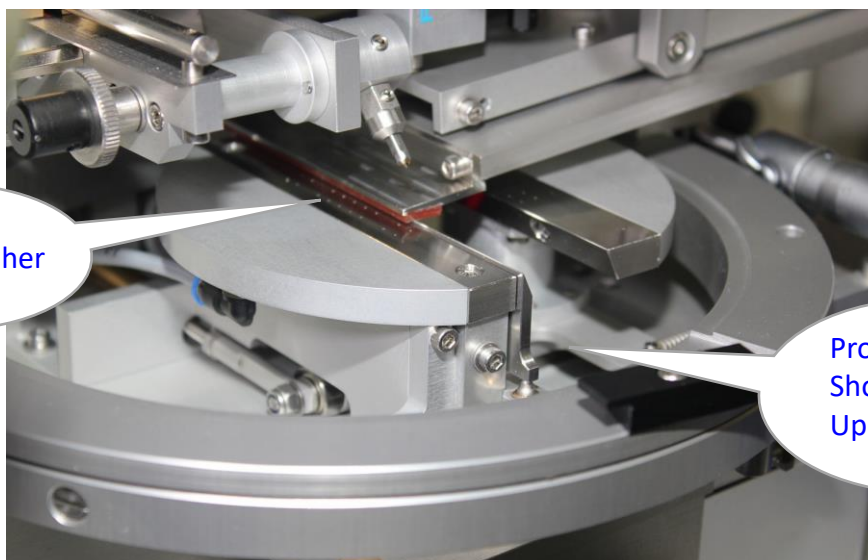


Pin for zero angle, mechanical reference

Adjustable weight for scribe force

Needle to watch the actual angle set-up

Diamond angular watch, to check diamond angular position



Rubber pusher

Programmable Shopper Blade, Up position

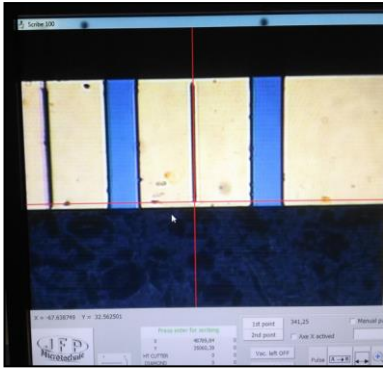
Shopper Blade used for breaking purposes, in conjunction with "Rubber pusher for break"

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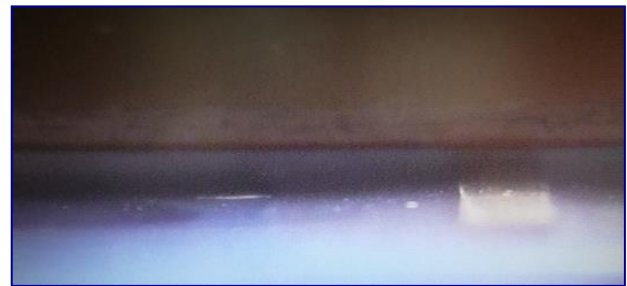


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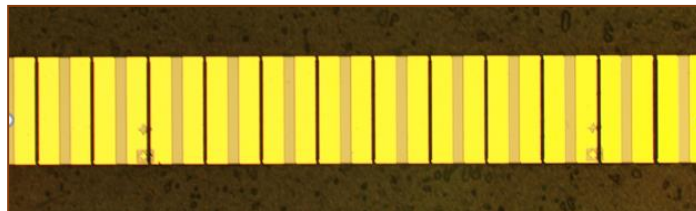
▶ Laser Bar to Laser Diodes Cycle



Scribe line



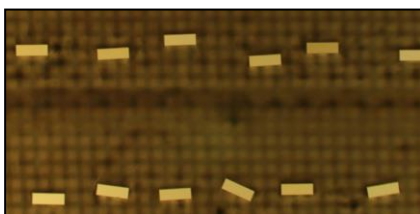
Break mode



Laser bar scribe and break



After sorting by
JFP PP One machine



Clean Facet

